

General Description

The MAX8845Z/MAX8845Y are intelligent, stand-alone constant-current, constant-voltage (CCCV), thermally regulated linear chargers designed for charging a single-cell lithium-ion (Li+) battery. The MAX8845Z/ MAX8845Y integrate a current-sense circuit, MOSFET pass element, thermal-regulation circuitry, and eliminates the external reverse-blocking Schottky diode to create the simplest and smallest charging solutions for handheld equipment.

The ICs control the charging sequence from the prequalification state through constant current fast-charge, top-off charge, and full-charge indication. Proprietary thermal-regulation circuitry limits the die temperature during fast-charging or when the ICs are exposed to high ambient temperatures, allowing maximum charging current without damaging the ICs.

The MAX8845Z/MAX8845Y achieve high flexibility by providing adjustable fast-charge currents (SETI) and an adjustable top-off current threshold (MIN) through external resistors. The MAX8845Z/ MAX8845Y feature a booting assistant circuit that distinguishes input sources and battery connection and provides an enable signal (ABO-MAX8845Z and ABO—MAX8845Y) for system booting.

The MAX8845Z/MAX8845Y also integrate an overvoltage-protected output (SAFEOUT) for low voltage-rated USB or charger inputs in system, and a battery-pack detection circuit (DETBAT) that disables the charger when the battery pack is absent. Other features include an active-low control input (EN), an active-low input power source detection output (POK), and a fully charged top-off threshold detection output (CHG).

The MAX8845Z/MAX8845Y accept an input supply range from 4.25V to 28V, but disables charging if the supply voltage exceeds +7.5V to protect against unqualified or faulty AC adapters. The IC's operate over the extended temperature range (-40°C to +85°C) and are available in a compact 12-pin, thermally enhanced thin QFN, 3mm x 3mm package (0.8mm max height).

Applications

Cellular and Cordless Phones Smart Phones and PDAs Digital Still Cameras MP3 Players **USB** Appliances Charging Cradles and Docks

Bluetooth® Equipment

Bluetooth is a registered trademark of Bluetooth SIG.

Features

- ♦ CCCV, Thermally Regulated Linear 1-Cell Li+ **Battery Charger**
- ♦ No External MOSFET, Reverse Blocking Diode, or **Current-Sense Resistor**
- ♦ Programmable Fast-Charge Currents (1A_{RMS} max)
- **♦** Programmable Top-Off Current Threshold (MIN)
- ♦ Input Overvoltage Protected 4.7V Output (SAFEOUT)
- **♦** Proprietary Die Temperature Regulation Control (+115°C)
- ♦ 4.25V to 28V Input Voltage Range with Input Overvoltage Protection Above +7.5V
- ♦ Low-Dropout Voltage (300mV at 500mA)
- ♦ Input Power-Source Detection Output (POK), Charge Status Output (CHG), Charge-Enable Input
- ♦ Output for Autobooting (ABO—MAX8845Z, ABO—MAX8845Y)
- ♦ Tiny, 3mm x 3mm 12-Pin Thin QFN Package, 0.8mm Height (max)

Ordering Information

PART	PART PIN-PACKAGE		PIN-PACKAGE TOI MAF		ABO ACTIVE STATE
MAX8845ZETC+	12 Thin QFN-EP*	ABL	Active high		
MAX8845YETC+	12 Thin QFN-EP*	ABM	Active low		

Note: All devices are specified over the -40°C to +85°C operating temperature range.

Typical Operating Circuit and Pin Configurations appear at end of data sheet.

⁺Denotes a lead(Pb)-free/RoHS-compliant package.

^{*}EP = Exposed pad.

ABSOLUTE MAXIMUM RATINGS

IN to GND
SAFEOUT to GND0.3V to +6V
IN to BATT Continuous Current1ARMS
Continuous Power Dissipation ($T_A = +70^{\circ}C$)
12-Thin QFN (derate 14.7mW/°C above +70°C)
(multilayer PCB)1176.5mW

BATT Short-Circuit Duration	Continuous
Operating Temperature Range	40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{IN}=5V, V_{BATT}=4V, R_{\overline{POK}}=1M\Omega$ to BATT, $\overline{EN}=$ unconnected, $R_{SETI}=2.8k\Omega$ to GND, $V_{DETBAT}=0$, $C_{BATT}=2.2\mu F$, $T_{A}=-40^{\circ}C$ to +85°C, unless otherwise noted. Typical values are at $T_{A}=+25^{\circ}C$.) (Note 1)

PARAMETER	CON	MIN	TYP	MAX	UNITS		
Input Supply Voltage Range			0		28	V	
Input Supply Operating Voltage Range			4.25		7.00	V	
Overvoltage Lockout Trip Threshold	V _{IN} rising, 100mV h	7.0	7.5	8.0	V		
	Constant current ch	0 0		0.22	0.50		
Input Current	Constant current ch		1		mA		
	IC disabled, $V_{\overline{EN}}$ =	5V		0.20	0.50		
	$V_{IN} = 4V$,	$T_A = +25^{\circ}C$		0.02			
	$V_{BATT} = 4.2V$	T _A = +85°C		0.03			
BATT, CHG, POK							
Minimum BATT Bypass Capacitance	Minimum BATT Bypass Capacitance					μF	
VBATT Prequalification Threshold Voltage	VBATT rising, 100m	V hysteresis (typ)	2.3	2.5	2.7	V	
Battery Regulation Voltage	$I_{BATT} = 0$ $T_A = -40^{\circ}$	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	4.175	4.200	4.225	V	
Battery riegulation voltage	18A11 = 0 1A = -40 0 to 403 0		4.158	4.200	4.242	V	
Regulator Dropout Voltage (VIN - VBATT)	$V_{BATT} = 4.1V, I_{BATT}$	r = 425mA		260		mV	
BATT Input Current	$V_{IN} = 0 \text{ to } 4V,$ $V_{BATT} = 4.2V$		5	10	μА		
	IC disabled		3				
Current-Sense Amplifier Gain (IBATT to ISETI)	I _{BATT} = 500mA			1016		μΑ/Α	
	V _{BATT} = 3.5V,	$T_A = 0$ °C to +85°C	460	500	540		
Foot Observe Occupant	$R_{SETI} = 2.8k\Omega$	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	425	500	575		
Fast-Charge Current	$V_{BATT} = 3.5V$, $R_{SETI} = 14k\Omega$ $T_A = 0^{\circ}C$ to $+85^{\circ}C$		85	100	115	mA	
CHG Top-Off Threshold	I_{BATT} falling, battery is charged $R_{MIN} = 1.75 k\Omega$			106		mA	
CHG Hysteresis	I_{BATT} rising after top $R_{MIN} = 1.75 k\Omega$		38		mA		
CHG Detection Delay	IBATT falls below top	p-off threshold	4.0	6.2	10.7	ms	

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ELECTRICAL CHARACTERISTICS (continued)

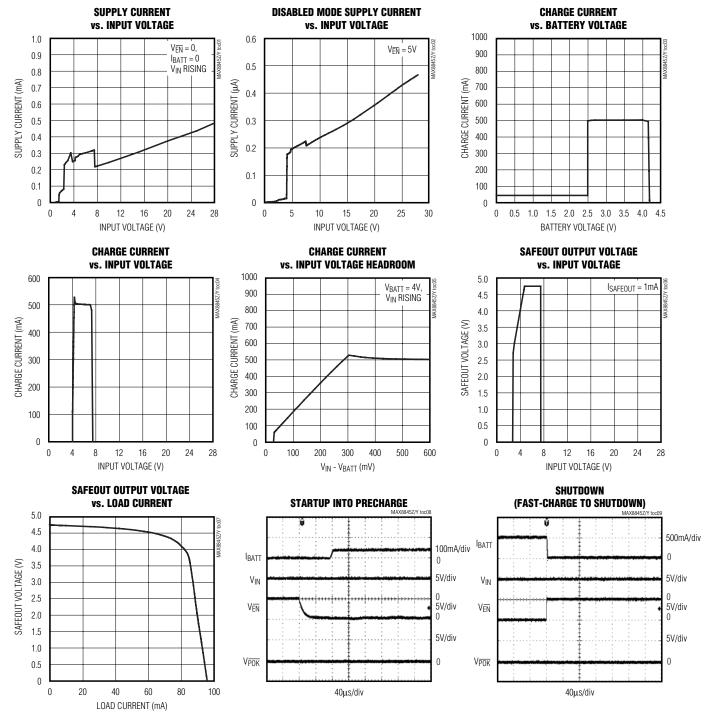
 $(V_{IN}=5V, V_{BATT}=4V, R_{\overline{POK}}=1M\Omega$ to BATT, $\overline{EN}=$ unconnected, $R_{SETI}=2.8k\Omega$ to GND, $V_{DETBAT}=0$, $C_{BATT}=2.2\mu F$, $T_{A}=-40^{\circ}C$ to $+85^{\circ}C$, unless otherwise noted. Typical values are at $T_{A}=+25^{\circ}C$.) (Note 1)

PARAMETER		TIONS	MIN	TYP	MAX	UNITS
Prequalification Charge Current	Percentage of the fast- charge current, V _{BATT} = 2.2V	charge current, V _{BATT} T _A = 0°C to +85°C		10	15	%
CHG, POK Output Low Threshold	$I_{\overline{POK}} = 5mA$, $I_{\overline{CHG}} = 5r$	nA			0.4	V
CHG, POK Output High Leakage Current	$V_{\overline{POK}} = 5.5V,$ $V_{\overline{CHG}} = 5.5V$	$T_A = +25$ °C $T_A = +85$ °C		0.01	1	μΑ
POK Threshold	V _{IN} - V _{BATT}	Vivirising		40 30		mV
DETBAT, SAFEOUT	1	•				·L
DETBAT Logic-Input Low Threshold					0.4	V
DETBAT Logic-Input High Threshold			1.3			V
DETBAT Pullup Resistor	DETBAT to V _L = 3V			470		kΩ
Minimum SAFEOUT Bypass Capacitance				1		μF
SAFEOUT Regulated Output	ISAFEOUT = 30mA, V _{IN} +85°C	ISAFEOUT = 30mA, V _{IN} = 5V, T _A = 0°C to +85°C			4.9	V
SAFEOUT Current Limit				100		mA
EN, ABI, ABO, ABO						
EN, ABI Internal Pulldown Resistor			100	200	400	kΩ
EN Logic-Input Low Threshold	$4.25V \le V_{IN} \le 7V$				0.4	V
EN Logic-Input High Threshold	$4.25V \le V_{IN} \le 7V$		1.3			V
ABI Logic-Input Low Threshold	$V_{BATT} = 4V, V_{IN} = 0$				0.4	V
ABI Logic-Input High Threshold	$V_{BATT} = 4V, V_{IN} = 0$		1.3			V
ABO Output Low Threshold (MAX8845Y)	Open drain, IABO(SINK)	= 1mA			0.4	V
ABO Output High Threshold (MAX8845Y)	Open drain, 100kΩ pullup to BATT		V _{BATT} - 0.4V			V
ABO Output Low Threshold (MAX8845Z)	IABO(SINK) = 1mA				0.4	V
ABO Output High Threshold (MAX8845Z)	IABO(SOURCE) = 1mA		V _{BATT} - 0.4V			V
THERMAL						
Die Temperature Regulation Threshold				115		°C

Note 1: Specifications are 100% production tested at T_A = +25°C. Limits over the operating temperature range are guaranteed by design and characterization.

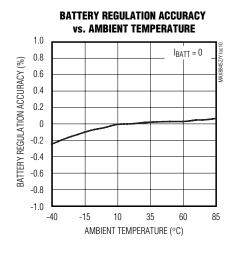
Typical Operating Characteristics

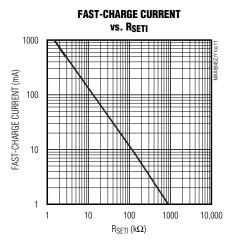
 $(V_{IN} = 5V, V_{BATT} = 4V, R_{\overline{POK}} = R_{\overline{CHG}} = 200k\Omega$ to $5V, \overline{EN} = unconnected$, $R_{SETI} = 2.8k\Omega$ to GND, $R_{MIN} = 1.74k\Omega$ to GND, $R_{DETBAT} = 4.7k\Omega$ to GND, $R_{DETBAT} = 4.7k\Omega$

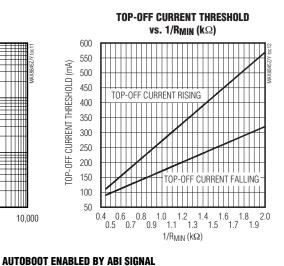


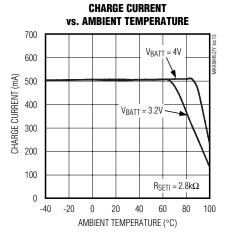
Typical Operating Characteristics (continued)

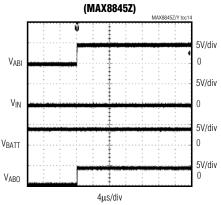
 $(V_{IN}=5V,V_{BATT}=4V,R_{\overline{POK}}=R_{\overline{CHG}}=200k\Omega$ to $5V,\overline{EN}=$ unconnected, $R_{SETI}=2.8k\Omega$ to GND, $R_{MIN}=1.74k\Omega$ to GND, $R_{DETBAT}=4.7k\Omega$ to GND, $R_{DETBAT}=4.7k\Omega$

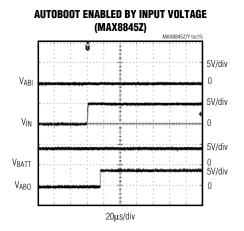


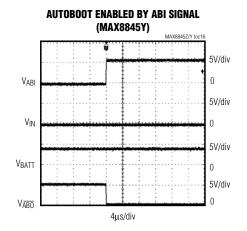












Pin Description

PIN			
MAX8845Z	MAX8845Y	NAME	FUNCTION
1	1	SETI	Charge-Current Program and Fast-Charge Current Monitor. Output current from SETI is 1016µA per ampere of battery charging current. Set the charging current by connecting a resistor (R _{SETI} in Figure 3) from SETI to GND. I _{FAST-CHARGE} = 1400V/R _{SETI} . To configure the MAX8845Z/MAX8845Y as a USB charger, see Figure 5.
2	2	DETBAT	Battery Pack ID Resistor Detection Input. If DETBAT is pulled low through a pulldown resistor less than 51k Ω the charger is enabled. If DETBAT is left unconnected, the charger is disabled.
3	3	ABI	Autobooting External Input. See the <i>Autobooting Assistant</i> section and Table 1 for autobooting conditions. ABI is pulled to GND through an internal $200k\Omega$ resistor.
4	4	ĒN	Active-Low, Logic-Level Enable Input. Drive $\overline{\text{EN}}$ high to disable charger. Drive $\overline{\text{EN}}$ low or leave unconnected for normal operation. $\overline{\text{EN}}$ has an internal 200k Ω pulldown resistor.
5	5	GND	Ground. Connect GND and the exposed pad to a large copper ground plane for maximum power dissipation. Connect GND to the exposed pad directly under the IC.
6	6	POK	Active-Low, Input Voltage Status Indicator. \overline{POK} is an open-drain output that asserts low when 2.35V < V _{IN} < 7V and (V _{IN} - V _{BATT}) \geq 40mV. If V _{IN} > +7.5V or V _{BATT} > V _{IN} the IC is shut down and \overline{POK} becomes high impedance. Connect a pullup resistor to the microprocessor's I/O voltage when interfacing with a microprocessor logic input.
7	_	ABO	Active-High, Autobooting Logic Output. See the <i>Autobooting Assistant</i> section and Table 1 for autobooting conditions.
_	7	ABO	Active-Low, Open-Drain Logic Output. See the <i>Autobooting Assistant</i> section and Table 1 for autobooting conditions.
8	8	BATT	Li+ Battery Connection. Bypass BATT to GND with a 2.2µF ceramic capacitor.
9	9	MIN	Top-Off Current Threshold Programmable Input. I _{MIN} (mA) falling = 148V/R _{MIN} (k Ω) + 22 (mA).
10	10	CHG	Active-Low, Charging Indicator. CHG is an open-drain output that is pulled low once charging begins. CHG is high impedance when the battery current drops below MIN, or when the IC is disabled. Connect a pullup resistor to the microprocessor's I/O voltage when interfacing with a microprocessor logic input.
11	11	IN	Input Supply Voltage. Bypass IN to GND with a 1µF or larger ceramic capacitor to improve line noise and input transient rejection.
12	12	SAFEOUT	4.7V Regulated LDO Output with Input Overvoltage Protection. Bypass SAFEOUT to GND with a 1µF or larger ceramic capacitor. SAFEOUT can be used to supply low voltage-rated USB systems.
— — ЕР		EP	Exposed Pad. Connect the exposed pad to a large ground plane for maximum power dissipation. Connect GND to the exposed pad directly under the IC.

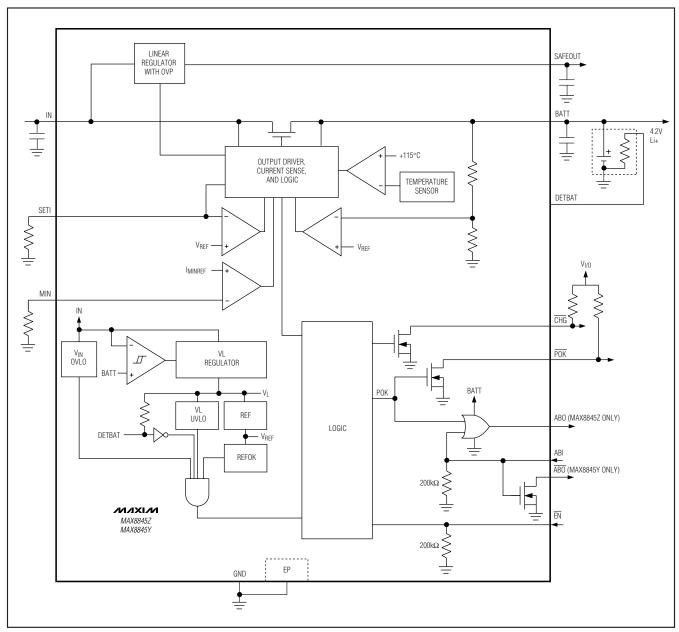


Figure 1. MAX8845Z/MAX8845Y Functional Diagram

Detailed Description

The MAX8845Z/MAX8845Y chargers use voltage, current, and thermal-control loops to charge a single Litcell and protect the battery (Figure 1). When a Li+ battery with a cell voltage below 2.5V is inserted, the MAX8845Z/MAX8845Y chargers enter a prequalification stage where it precharges that cell with 10% of the

user-programmed fast-charge current (Figure 2). The CHG indicator is driven low to indicate entry into the prequalification state. When the battery voltage exceeds 2.5V, the charger soft-starts as it enters the fast-charge stage. The fast-charge current level is programmed through a resistor from SETI to GND. As the battery voltage approaches 4.2V, the charging current

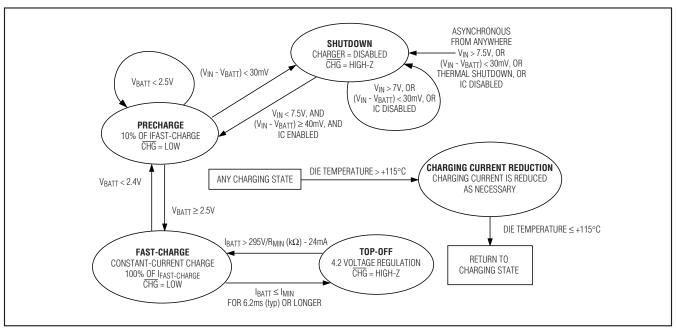


Figure 2. Charge-State Diagram

is reduced. If the battery current drops to less than the top-off current threshold set by R_{MIN}, the charger enters top-off mode and the CHG indicator goes high impedance signaling that the battery is fully charged.

Overvoltage-Protected Output (SAFEOUT)

SAFEOUT is a linear regulator that provides an output voltage of 4.7V and can be used to supply low voltage-rated USB systems. The SAFEOUT linear regulator turns on when $V_{\text{IN}} \geq 4.25 \text{V}$ regardless of $\overline{\text{EN}}$ and is disabled when V_{IN} is greater than the overvoltage threshold (7.5V typ).

Battery-Pack Detection Input (DETBAT)

DETBAT is a battery-pack ID resistor detector that enables the battery charger if pulled low through a resistor that is less than $51k\Omega$. If DETBAT is left unconnected or the pulldown resistor is $51k\Omega$ or greater the battery charger is disabled. If DETBAT is not used connect DETBAT to GND for normal operation.

POK Output

The open-drain \overline{POK} output asserts low when $2.35V \le V_{IN} \le 7V$, $(V_{IN} - V_{BATT}) \ge 40 \text{mV}$ (typ V_{IN} rising), and DETBET is pulled low through a resistor that is less than $51 \text{k}\Omega$. \overline{POK} is high impedance during shutdown. When interfacing with a microprocessor logic input, a pullup resistor to the microprocessor's I/O voltage may be required.

Autobooting Assistant

The MAX8845Z/MAX8845Y contain autobooting assistant circuits that generate an enable signal for system booting (ABO—MAX8845Z, \overline{ABO} —MAX8845Y). For the MAX8845Z, the booting assistant functions as an internal OR gate (Figure 1). The first input is dependant on the input voltage (V_{IN}) and DETBAT while the second input is an external signal applied to ABI. The first input (\overline{POK}) is driven high once DETBAT is pulled low through a resistor less than $51k\Omega$, $2.35V \le V_{IN} \le 7V$, and $(V_{IN} - V_{BATT}) \ge 40mV$ (typ V_{IN} rising).

The second input signal (ABI) is driven by an external source (Table 1). ABI enables an autoboot signal when a battery is connected at BATT and is independent of $\overline{\text{POK}}$. If $\overline{\text{POK}}$ is pulled low, the booting assistant always drives ABO high regardless of ABI. ABI is pulled to GND through an internal 200k Ω resistor. If ABI is supplied from an outside exposed pin, a RC filter (Figure 4) is required for ESD protection and noise filtering. If ABI is supplied by a system's internal GPIO, or logic, the RC filter is not required. For the MAX8845Y, the output $\overline{\text{ABO}}$ is only dependent on the state of ABI (Table 1).

CHG Charge Indicator Output

CHG is an open-drain output that indicates charge status. Table 2 describes the state of CHG during different stages of operation. CHG is suitable for driving a charge indication LED. If the MAX8845Z/MAX8845Y are

Table 1. Autobooting Output States

ABI	BATT	POK	CHARGER STATE	ABO (MAX8845Z)	ABO (MAX8845Y)
Low	Present	High-Z	Shutdown	Low	High-Z
High	Present	High-Z	Shutdown	High	Low
Low	Not present	Low	CC/CV mode	High	High-Z
Low	Present	Low	Fast-charge/top-off	High	High-Z
High	Present	Low	Fast-charge/top-off	High	Low

Note: Present indicates that V_{BATT} ≥ 2V and Not Present indicates that the battery is not connected.

Table 2. CHG States

ĒN	V _{IN}	V _{BATT}	IBATT	CHG	STATE	
High	X	Χ	X 0		Disabled	
Low	> 7.5V	X	0	∐igh 7	Shutdown	
Low	X	> V _{IN} - 30mV	U	High-Z	Shuldown	
Low	4.25V ≤ V _{IN} ≤ 7.5V	< 2.4V	10% of IFAST-CHARGE*	Low	Precharge	
Low	$4.25V \le V_{1N} \le 7.5V$	≥ 2.5V	100% of IFAST-CHARGE*	Low	Fast-charge	
Low	$4.25V \le V_{IN} \le 7.5V$	4.2V	< IMIN	High-Z	Top-off	

X = Don't care.

used in conjunction with a microprocessor, a pullup resistor to the logic I/O voltage allows $\overline{\text{CHG}}$ to indicate charge status to the microprocessor instead of driving an LED.

Thermal Regulation

The thermal-regulation loop limits the MAX8845Z/MAX8845Y die temperature to +115°C by reducing the charge current as necessary. This feature not only protects the IC from overheating, but also allows a higher charge current without risking damage to the system.

Charger Enable Input

The MAX8845Z/MAX8845Y contain active-low logic input (\overline{EN}) used to enable the chargers. Drive \overline{EN} low, leave unconnected, or connect to GND to enable the charge-control circuitry. Drive \overline{EN} high to disable the charger-control circuitry. \overline{EN} has an internal 200k Ω pull-down resistor.

Soft-Start

The soft-start algorithm activates when entering fast-charge mode. When the prequalification state is complete (V_{BATT} exceeds +2.5V), the charging current ramps up in 250µs to the full charging current. This reduces the inrush current demand on the input supply.

Applications Information

Fast Charge-Current Setting

The maximum charging current is programmed by an external resistor connected from SETI to GND (RSETI). Use the following equation to determine the fast-charge current (IFAST_CHARGE):

$$I_{FAST_CHARGE} = \frac{1400V}{R_{SETI}}$$

where IFAST_CHARGE is in amps and RSETI is in ohms. RSETI must always be 1.4k Ω or higher due to the continuous charging current limit of 1ARMS.

Top-Off Current Threshold Setting

The top-off current threshold is programmed by an external resistor connected from MIN to GND (R_{MIN}). Use the following equation to determine the top-off current (I_{MIN}):

 I_{MIN} (falling) = 148V/R_{MIN} (k Ω) + 22mA I_{MIN} (rising) = 295V/R_{MIN} (k Ω) - 24mA

where I_{MIN} is in mA and R_{MIN} is in k Ω . Use R_{MIN} \leq 2.2k Ω .

^{*}IFAST-CHARGE is reduced as necessary to prevent the die temperature from exceeding +115°C.

Capacitor Selection

Connect a ceramic capacitor from BATT to GND for proper stability. Use a $2.2\mu F$ ceramic capacitor for most applications. Connect a $1\mu F$ ceramic capacitor from IN to GND. A larger input capacitor can be used for high charging current to reduce input voltage ripple.

Connect a $1\mu F$ ceramic capacitor from SAFEOUT to GND. A larger bypass capacitor for SAFEOUT can be used for optimum noise immunity. Ceramic capacitors with X5R or X7R dielectric are highly recommended due to their small size, low ESR, and small temperature coefficients.

Thermal Considerations

The MAX8845Z/MAX8845Y are available in thermally enhanced Thin QFN packages with exposed pads. Connect the exposed pad to a large copper ground plane to provide a thermal contact between the device and the circuit board for increased power dissipation. The exposed pad transfers heat away from the device, allowing the IC to charge the battery with maximum current, while minimizing the increase in die temperature.

DC Input Sources

The MAX8845Z/MAX8845Y operate from well-regulated DC sources. The full charging input voltage range is 4.25V to 7.5V. The device can withstand up to 28V on the input without damage to the IC. If V_{IN} is greater than 7.5V, the internal overvoltage-protection circuitry disables charging until the input falls below 7.5V. An appropriate power supply must provide at least 4.25V at the desired peak charging current and stay below 7V when unloaded.

Typical Application Circuits

AC Adapter Application

Figure 3 shows the MAX8845Z as a Li+ battery charger with an AC adapter. The MAX8845Z detects the presence of an input supply and DETBET, resulting in POK pulled low. Once POK is pulled low, the autobooting assistant drives ABO high (MAX8845Z) and enables the power supplies of the system to boot up. The MAX8845Z begins charging the battery when EN is low or unconnected. By monitoring CHG, the system can detect the top-off threshold and terminate the charge through EN. The MAX8845Z/MAX8845Y also provide an overvoltage-protected SAFEOUT to the system.

Factory System Interface Connector Application

Figure 4 shows the MAX8845Z as an autoboot assistor with the factory system interface connector. The MAX8845Z detects the ABI input even though there is no input voltage available and generates an ABO signal to turn on power supplies to boot up the system. The configuration in Figure 4 is used for system development, testing, and calibrations in production or design stage.

USB-Powered Li-Ion Charger

The universal serial bus (USB) provides a high-speed serial communication port as well as power for the remote device. The MAX8845Z/MAX8845Y can be configured to charge batteries at the highest current possible from the host port. Figure 5 shows the MAX8845Z as a USB battery charger. To make the circuit compatible with either 100mA or 500mA USB ports, the circuit initializes at 100mA charging current. The microprocessor then enumerates the host to determine its current capability. If the host port is capable, the charging current is increased to 450mA to avoid exceeding the 500mA USB specification through GPIO control. The MAX8845Z/MAX8845Y also provide an overvoltage-protected SAFEOUT to the system.

Recommended PCB Layout and Routing

Place all bypass capacitors for IN, BATT, and SAFEOUT as close as possible to the device. Connect the battery to BATT as close as possible to the device to provide accurate battery voltage sensing. Provide a large copper ground plane to allow the exposed pad to sink heat away from the device. Make all high-current traces short and wide to minimize voltage drops. A sample layout is available in the MAX8845Z Evaluation Kit to speed designs.

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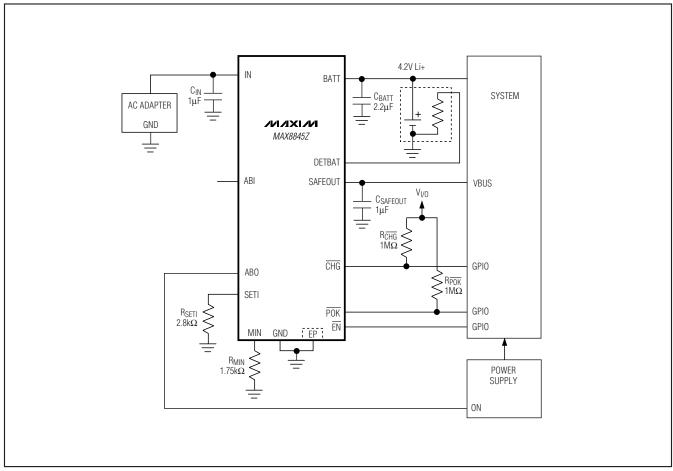


Figure 3. AC Adapter Application

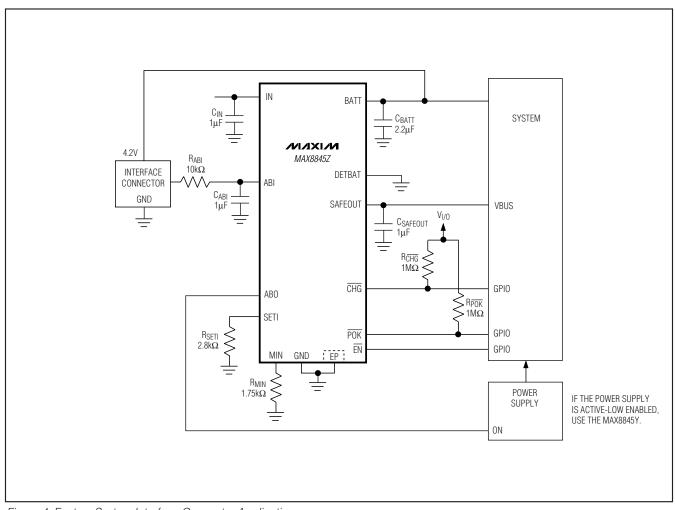


Figure 4. Factory System Interface Connector Application

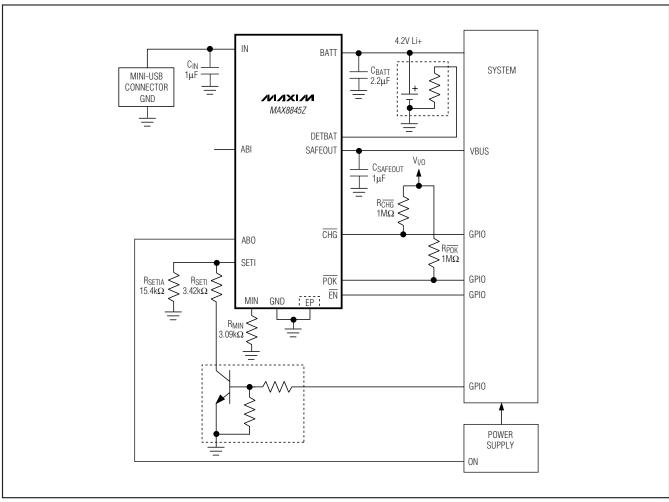


Figure 5. Mini USB Battery Charger

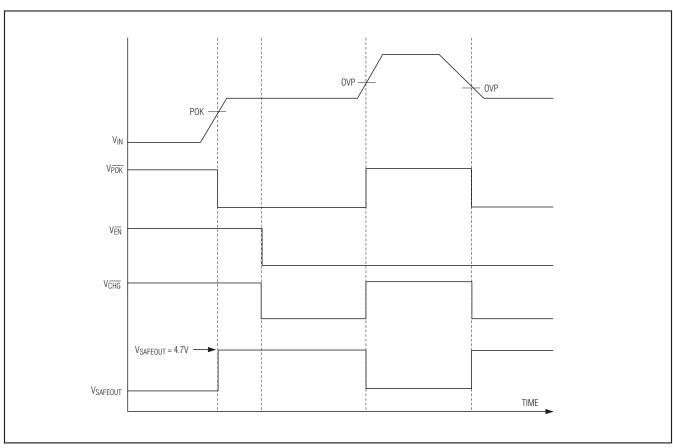
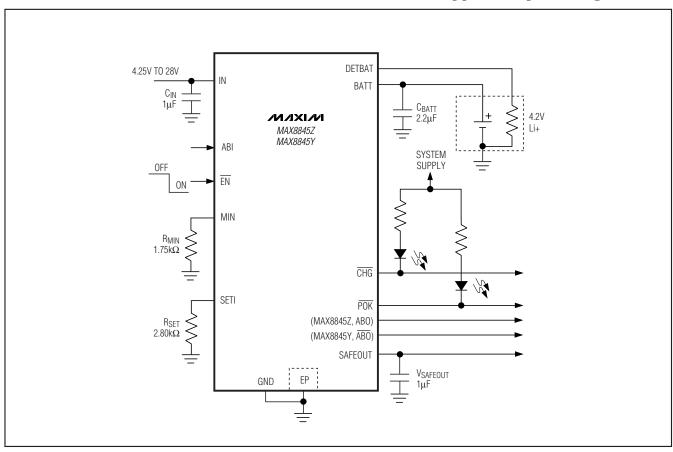
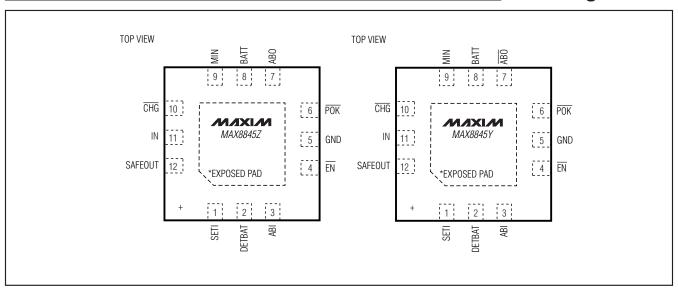


Figure 6. Timing Diagram

_Typical Operating Circuit



Pin Configurations



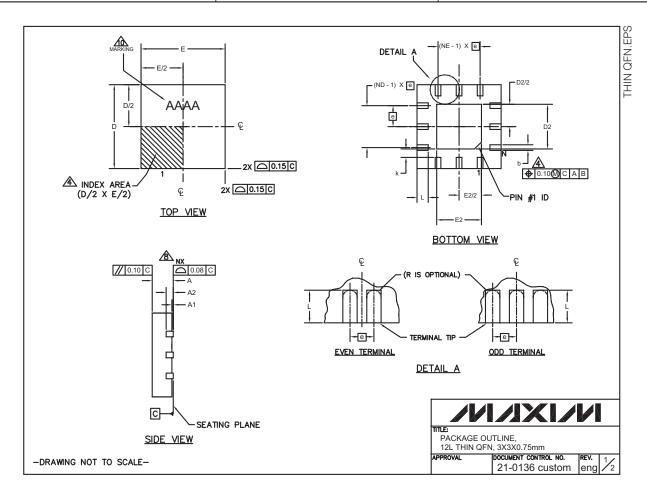
_____Chip Information

PROCESS: BiCMOS

Package Information

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages

PACKAGE TYPE	PACKAGE CODE	DOCUMENT NO.
12 Thin QFN-EP (3mm x 3mm)	T1233-4	<u>21-0136</u>



Package Information (continued)

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages.

PKG	1	3		
REF.	MIN.	NOM.	MAX.	
Α	0.70	0.75	0.80	
b	0.20	0.25	0.30	
D	2.90	3.00	3.10	
Е	2.90	3.00	3.10	
е	0	.50 BSC.		
L	0.45	0.55	0.65	
N		12		
ND		3		
NE		3		
A1	0	0.02	0.05	
A2	0	.20 RE	F	
k	0.25	-	-	

		EXF	OSE	D PAE) VAR	IATIC	NS	
PKG.	D2			E2		DIN ID	JEDEC	
CODES	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	PIN ID	JEDEC
T1233-1	0.95	1.10	1.25	0.95	1.10	1.25	0.35 x 45°	WEED-1
T1233-3	0.95	1.10	1.25	0.95	1.10	1.25	0.35 x 45°	WEED-1
T1233-4	0.95	1.10	1.25	0.95	1.10	1.25	0.35 x 45°	WEED-1

- 1. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.
 - N IS THE TOTAL NUMBER OF TERMINALS.
- 1 THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION SHALL CONFORM TO JESD 95-1 SPP-012. DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE TERMINAL #1 IDENTIFIER MAY BE EITHER A MOLD OR
- ⚠ DIMENSION b APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.20 mm AND 0.25 mm FROM TERMINAL TIP.
- 6 ND AND NE REFER TO THE NUMBER OF TERMINALS ON EACH D AND E SIDE RESPECTIVELY.
- DEPOPULATION IS POSSIBLE IN A SYMMETRICAL FASHION.
- COPLANARITY APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.
- DRAWING CONFORMS TO JEDEC MO220 REVISION C. DRAWING CONFORMS TO JEDEC MO220 REVISION C.
 MARKING IS FOR PACKAGE ORIENTATION REFERENCE ONLY.
- 11. NUMBER OF LEADS SHOWN ARE FOR REFERENCE ONLY.
- 12. WARPAGE NOT TO EXCEED 0.10mm

PACKAGE OUTLINE

12L THIN QFN, 3X3X0.75mm

DOCUMENT CONTROL NO. 21-0136 custom

-DRAWING NOT TO SCALE-

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